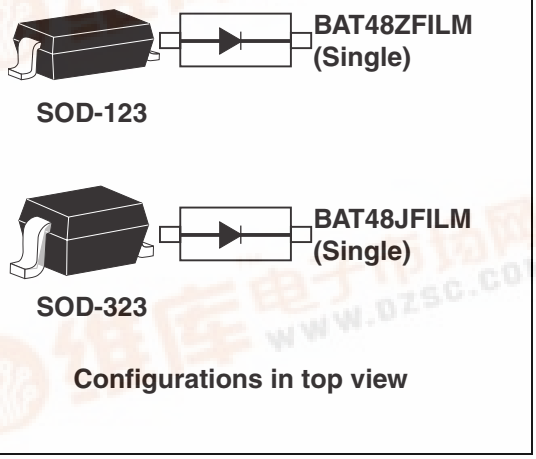
BAT48 Series

Small signal Schottky diodes

Main product characteristics

I_F	350 mA
V_{RRM}	40 V
C (typ)	18 pF
T_j (max)	150° C



Configurations in top view

Features and benefits

- Low leakage current losses
- Negligible switching losses
- Low forward and reverse recovery times
- Extremely fast switching
- Surface mount device
- Low capacitance diode

Description

The BAT48 series uses 40 V Schottky barrier diodes packaged in SOD-123 or SOD-323. This series is general purpose and features very low turn-on voltage and fast switching

Order codes

Part Number	Marking
BAT48ZFILM	Z48
BAT48JFILM	48

Table 1. Absolute ratings (limiting values at T_j = 25° C, unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		40	V
I_F	Continuous forward current		350	mA
I_{FSM}	Surge non repetitive forward current	t_p = 10 ms Sinusoidal	2	A
T_{stg}	Storage temperature range		-65 to +150	° C
T_j	Maximum operating junction temperature		150	° C

1 Characteristics

Table 2. Thermal parameters

Symbol	Parameter		Value	Unit
$R_{th(j-a)}$	Junction to ambient(1)	SOD-123	500	°C/W
		SOD-323	550	

1. Epoxy printed circuit board with recommended pad layout

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ	Max.	Unit
V_{BR}	Breakdown reverse voltage	T_j = 25° C	I_r = 25 µA	40			V
I_R(1)	Reverse leakage current	T_j = 25° C	V_R = 1.5 V			1	µA
			V_R = 10 V			2	
			V_R = 20 V			5	
			V_R = 40 V			25	
		T_j = 60° C	V_R = 1.5 V			10	
			V_R = 10 V			15	
			V_R = 20 V			25	
			V_R = 40 V			50	
V_F(2)	Forward voltage drop	T_j = 25° C	I_F = 0.1 mA			0.25	V
			I_F = 1 mA			0.3	
			I_F = 10 mA			0.4	
			I_F = 50 mA			0.5	
			I_F = 200 mA			0.75	
			I_F = 500 mA			0.9	

1. Pulse test: t_p = 5 ms, δ < 2 %
2. Pulse test: t_p = 380 µs, δ < 2 %

Table 4. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ	Max.	Unit
C	Diode capacitance	V_R = 0 V, F = 1 MHz		30		pF
		V_R = 1 V, F = 1 MHz		18		

Figure 1. Average forward power dissipation versus average forward current

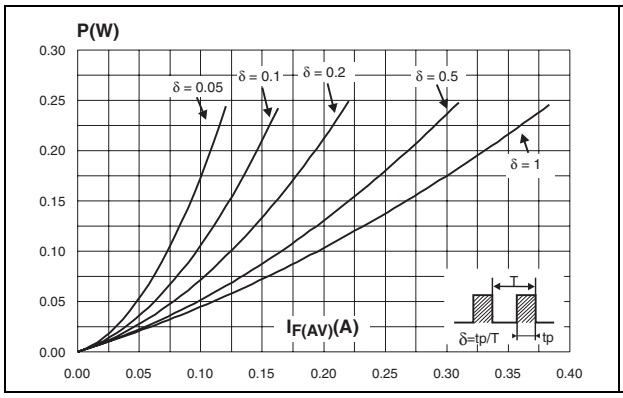


Figure 2. Average forward current versus ambient temperature (δ = 1)

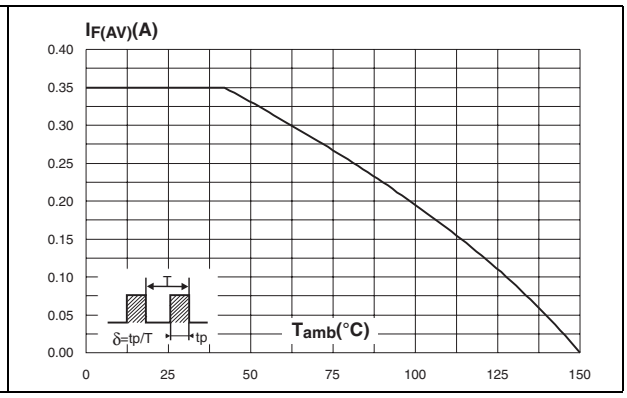


Figure 3. Reverse leakage current versus reverse applied voltage (typical values)

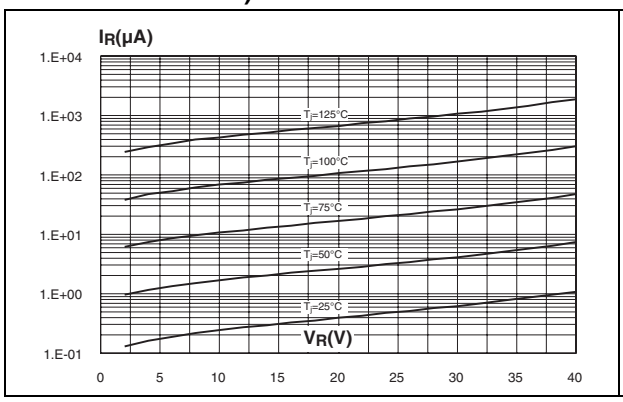


Figure 4. Reverse leakage current versus junction temperature (typical values)

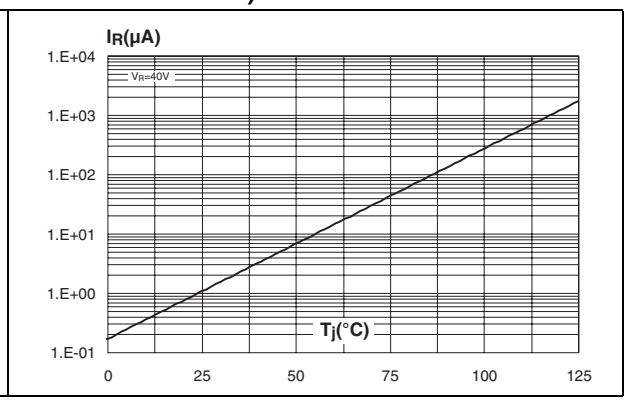


Figure 5. Junction capacitance versus reverse applied voltage (typical values)

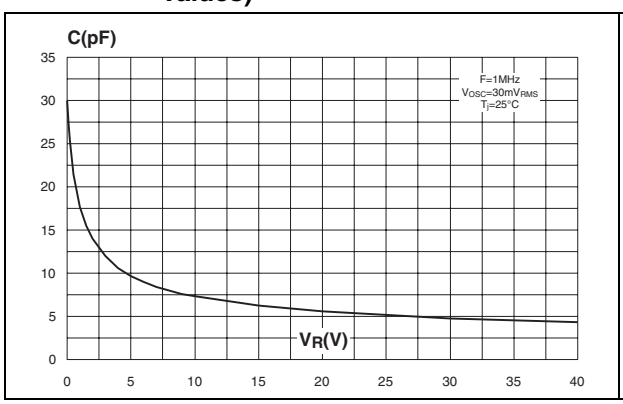


Figure 6. Forward voltage drop versus forward current (typical values)

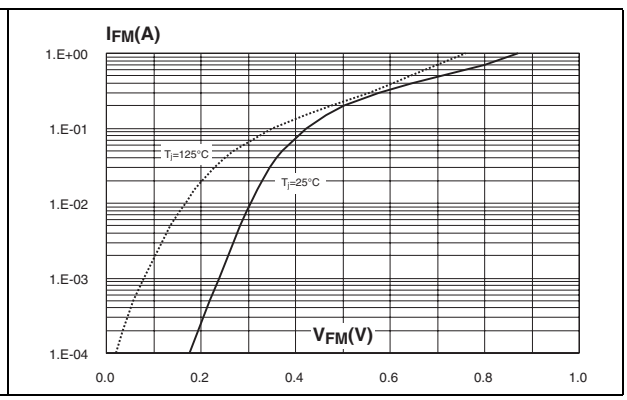


Figure 7. Relative variation of thermal impedance junction to ambient versus pulse duration (epoxy FR4 with recommended pad layout, e_{CU} = 35 µm) (SOD-323)

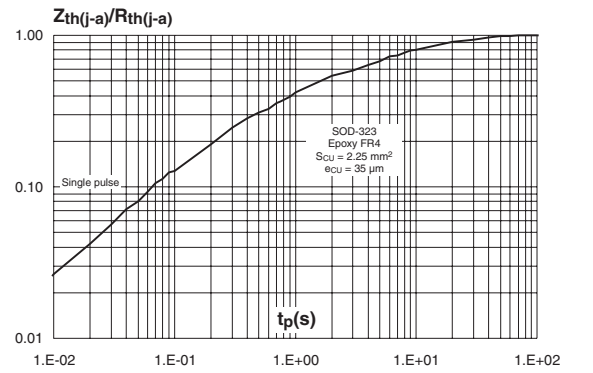
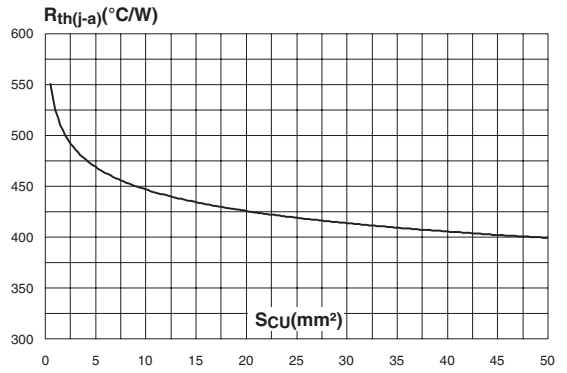
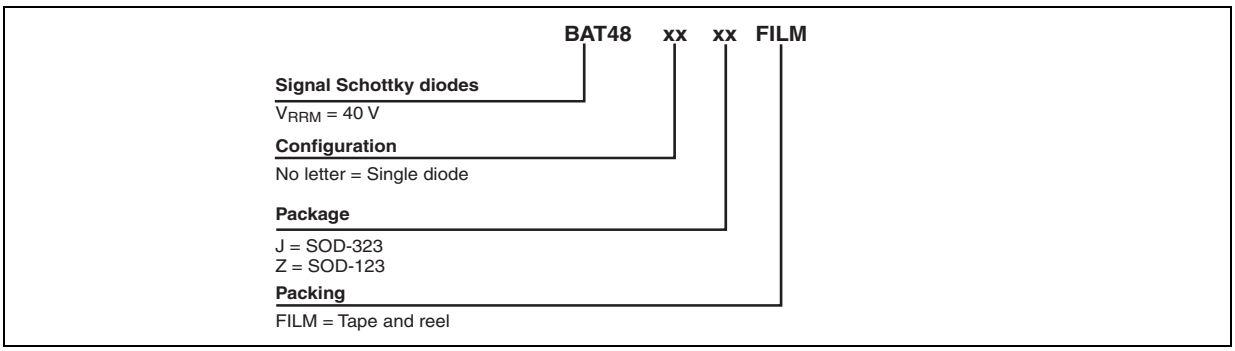


Figure 8. Thermal resistance junction to ambient versus copper surface under each lead (printed circuit board, epoxy FR4, e_{CU}=35 µm, SOD-323)



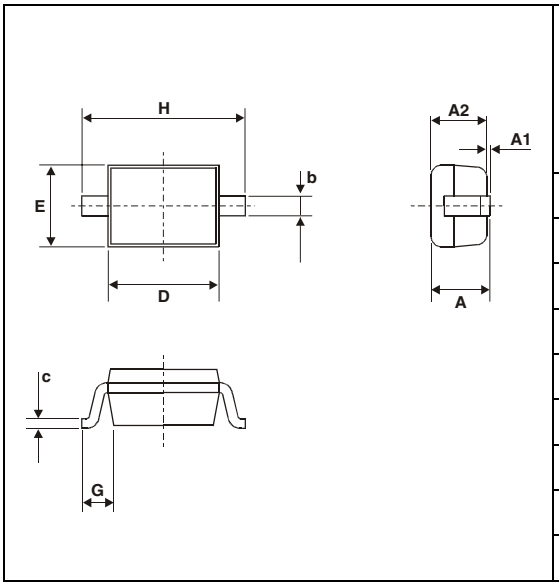
2 Ordering information scheme



3 Package information

Epoxy meets UL94, V0

Table 5. SOD-123 dimensions



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A		1.45		0.057
A1	0	0.1	0	0.004
A2	0.85	1.35	0.033	0.053
b	0.55 Typ.		0.022 Typ.	
c	0.15 Typ.		0.039 Typ.	
D	2.55	2.85	0.1	0.112
E	1.4	1.7	0.055	0.067
G	0.25		0.01	
H	3.55	3.95	0.14	0.156

Figure 9. SOD-123 footprint (dimensions in mm)

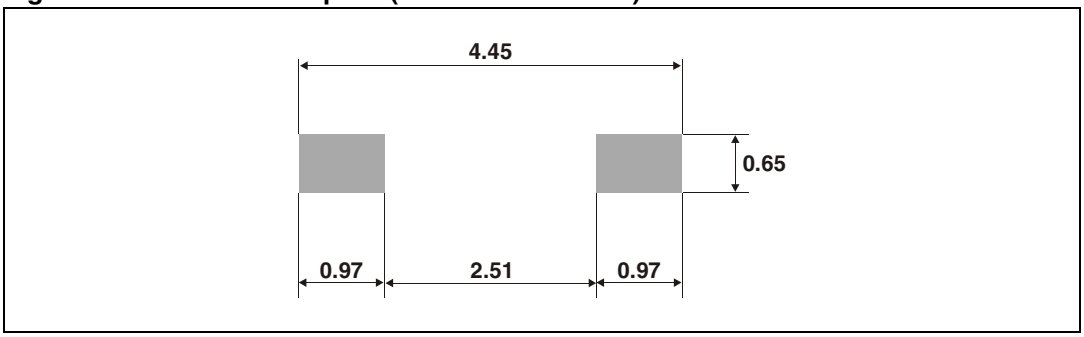
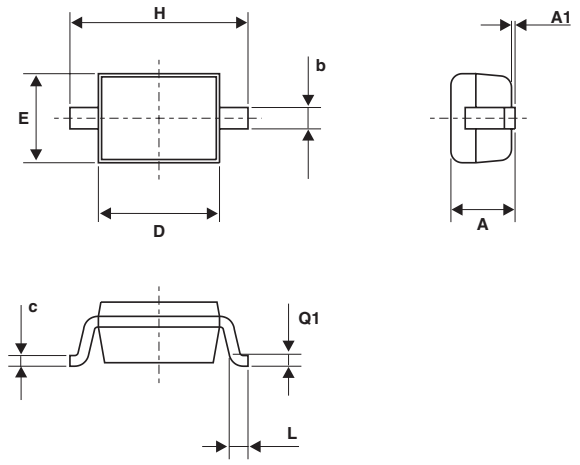
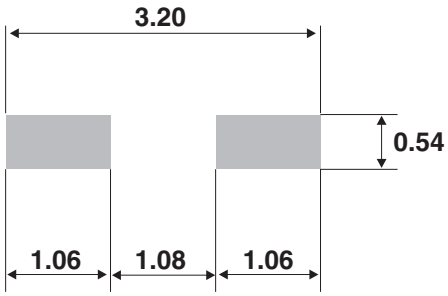


Table 6. SOD-323 dimensions



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A		1.17		0.046
A1	0	0.1	0	0.004
b	0.25	0.44	0.01	0.017
c	0.1	0.25	0.004	0.01
D	1.52	1.8	0.06	0.071
E	1.11	1.45	0.044	0.057
H	2.3	2.7	0.09	0.106
L	0.1	0.46	0.004	0.02
Q1	0.1	0.41	0.004	0.016

Figure 10. SOD-323 footprint (dimensions in mm)



In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

4 Ordering information

Part Number	Marking	Package	Weight	Base qty	Delivery mode
BAT48ZFILM	Z48	SOD-123 Single	10 mg	3000	Tape and reel
BAT48JFILM	48	SOD-323 Single	5 mg	3000	Tape and reel

5 Revision history

Date	Revision	Description of Changes
08-Aug-2006	1	Initial release.

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